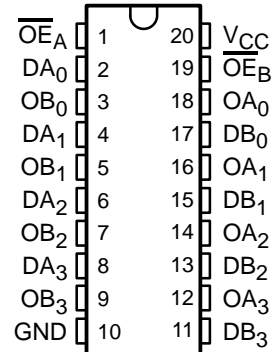


# CY54FCT244T, CY74FCT244T 8-BIT BUFFERS/LINE DRIVERS WITH 3-STATE OUTPUTS

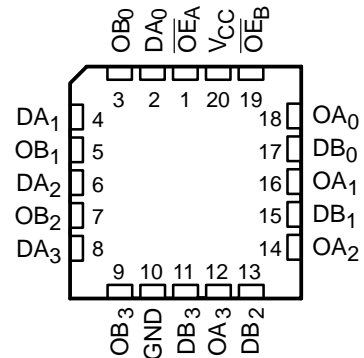
SCCS071 – OCTOBER 2001

- Function, Pinout, and Drive Compatible With FCT and F Logic
- Reduced  $V_{OH}$  (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)
- Matched Rise and Fall Times
- Fully Compatible With TTL Input and Output Logic Levels
- CY54FCT244T
  - 48-mA Output Sink Current
  - 12-mA Output Source Current
- CY74FCT244T
  - 64-mA Output Sink Current
  - 32-mA Output Source Current
- 3-State Outputs

CY54FCT244T . . . D PACKAGE  
CY74FCT244T . . . P, Q, OR SO PACKAGE  
(TOP VIEW)



CY54FCT244T . . . L PACKAGE  
(TOP VIEW)



## description

The 'FCT244T devices are octal buffers and line drivers designed to be employed as memory address drivers, clock drivers, and bus-oriented transmitters/receivers. These devices provide speed and drive capabilities equivalent to their fastest bipolar logic counterparts, while reducing power consumption. The input and output voltage levels allow direct interface with TTL, NMOS, and CMOS devices without external components.

These devices are fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

**CY54FCT244T, CY74FCT244T**  
**8-BIT BUFFERS/LINE DRIVERS**  
**WITH 3-STATE OUTPUTS**

SCCS071 – OCTOBER 2001

**ORDERING INFORMATION**

T <sub>A</sub>	PACKAGE†		SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	QSOP – Q	Tape and reel	3.6	CY74FCT244DTQCT	FCT244D
	SOIC – SO	Tube	3.6	CY74FCT244DTSOC	FCT244D
		Tape and reel	3.6	CY74FCT244DTSOCT	
–40°C to 85°C	SOIC – SO	Tube	4.1	CY74FCT244CTSOC	FCT244C
		Tape and reel	4.1	CY74FCT244CTSOCT	
	QSOP – Q	Tape and reel	4.1	CY74FCT244CTQCT	FCT244C
	DIP – P	Tube	4.6	CY74FCT244ATPC	CY74FCT244ATPC
	SOIC – SO	Tube	4.6	CY74FCT244ATSOC	FCT244A
		Tape and reel	4.6	CY74FCT244ATSOCT	
	QSOP – Q	Tape and reel	4.6	CY74FCT244ATQCT	FCT244A
	SOIC – SO	Tube	6.5	CY74FCT244TSOC	FCT244
		Tape and reel	6.5	CY74FCT244TSOCT	
	QSOP – Q	Tape and reel	6.5	CY74FCT244TQCT	FCT244
	–55°C to 125°C	CDIP – D	Tube	4.6	CY54FCT244CTDMB
LCC – L		Tube	4.6	CY54FCT244CTLMB	
CDIP – D		Tube	5.1	CY54FCT244ATDMB	
LCC – L		Tube	5.1	CY54FCT244ATLMB	
CDIP – D		Tube	7	CY54FCT244TDMB	
LCC – L		Tube	7	CY54FCT244TLMB	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

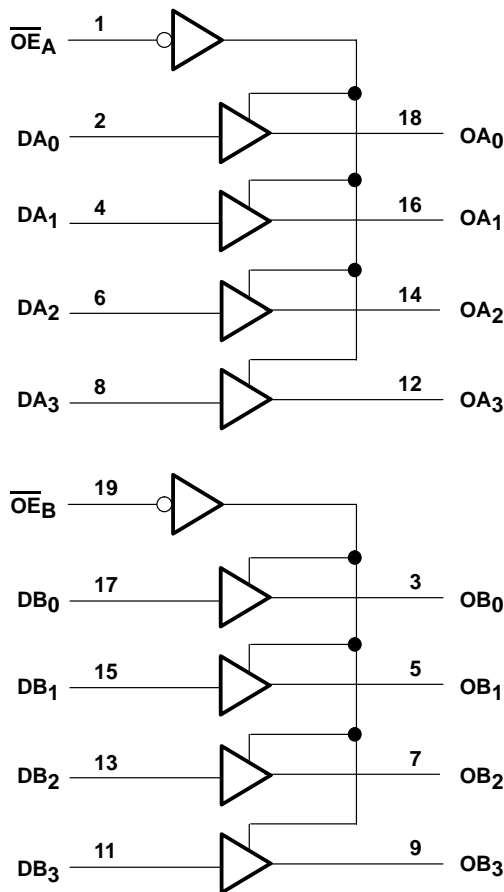
**FUNCTION TABLE**

INPUTS			OUTPUT
$\overline{OE}_A$	$\overline{OE}_B$	D	O
L	L	L	L
L	L	H	H
H	H	X	Z

H = High logic level, L = Low logic level,  
X = Don't care, Z = High-impedance state



logic diagram (positive logic)



absolute maximum rating over operating free-air temperature range (unless otherwise noted)†

Supply voltage range to ground potential .....	-0.5 V to 7 V
DC input voltage range .....	-0.5 V to 7 V
DC output voltage range .....	-0.5 V to 7 V
DC output current (maximum sink current/pin) .....	120 mA
Package thermal impedance, $\theta_{JA}$ (see Note 1): P package .....	69°C/W
Q package .....	68°C/W
SO package .....	58°C/W
Ambient temperature range with power applied, $T_A$ .....	-65°C to 135°C
Storage temperature range, $T_{Stg}$ .....	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

**CY54FCT244T, CY74FCT244T**  
**8-BIT BUFFERS/LINE DRIVERS**  
**WITH 3-STATE OUTPUTS**

SCCS071 – OCTOBER 2001

**recommended operating conditions (see Note 2)**

	CY54FCT244T			CY74FCT244DT			CY74FCT244T			UNIT			
	MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX				
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	4.75	5	5.25	V			
V <sub>IH</sub> High-level input voltage	2			2			2			V			
V <sub>IL</sub> Low-level input voltage	0.8			0.8			0.8			V			
I <sub>OH</sub> High-level output current	-12			-32			-32			mA			
I <sub>OL</sub> Low-level output current	48			64			64			mA			
T <sub>A</sub> Operating free-air temperature	-55			125			0			70	-40	85	°C

NOTE 2: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation.



**CY54FCT244T, CY74FCT244T**  
**8-BIT BUFFERS/LINE DRIVERS**  
**WITH 3-STATE OUTPUTS**

SCCS071 – OCTOBER 2001

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	CY54FCT244T		CY74FCT244T		UNIT
		MIN	TYP†	MAX	MIN	
V <sub>IK</sub>	V <sub>CC</sub> = 4.5 V, I <sub>IN</sub> = -18 mA	-0.7	-1.2			V
	V <sub>CC</sub> = 4.75 V, I <sub>IN</sub> = -18 mA			-0.7	-1.2	
V <sub>OH</sub>	V <sub>CC</sub> = 4.5 V, I <sub>OH</sub> = -12 mA	2.4	3.3			V
	V <sub>CC</sub> = 4.75 V	I <sub>OH</sub> = -32 mA		2		
		I <sub>OH</sub> = -15 mA		2.4	3.3	
V <sub>OL</sub>	V <sub>CC</sub> = 4.5 V, I <sub>OL</sub> = 48 mA	0.3	0.55			V
	V <sub>CC</sub> = 4.75 V, I <sub>OL</sub> = 64 mA			0.3	0.55	
V <sub>hys</sub>	All inputs	0.2		0.2		V
I <sub>I</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = V <sub>CC</sub>			5		μA
	V <sub>CC</sub> = 5.25 V, V <sub>IN</sub> = V <sub>CC</sub>				5	
I <sub>IH</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 2.7 V			±1		μA
	V <sub>CC</sub> = 5.25 V, V <sub>IN</sub> = 2.7 V				±1	
I <sub>IL</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 0.5 V			±1		μA
	V <sub>CC</sub> = 5.25 V, V <sub>IN</sub> = 0.5 V				±1	
I <sub>OZH</sub>	V <sub>CC</sub> = 5.5 V, V <sub>OUT</sub> = 2.7 V			10		μA
	V <sub>CC</sub> = 5.25 V, V <sub>OUT</sub> = 2.7 V				10	
I <sub>OZL</sub>	V <sub>CC</sub> = 5.5 V, V <sub>OUT</sub> = 0.5 V			-10		μA
	V <sub>CC</sub> = 5.25 V, V <sub>OUT</sub> = 0.5 V				-10	
I <sub>OS</sub> ‡	V <sub>CC</sub> = 5.5 V, V <sub>OUT</sub> = 0 V	-60	-120	-225		mA
	V <sub>CC</sub> = 5.25 V, V <sub>OUT</sub> = 0 V				-60 -120 -225	
I <sub>off</sub>	V <sub>CC</sub> = 0 V, V <sub>OUT</sub> = 4.5 V			±1		μA
I <sub>CC</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> ≤ 0.2 V, V <sub>IN</sub> ≥ V <sub>CC</sub> - 0.2 V	0.1	0.2			mA
	V <sub>CC</sub> = 5.25 V, V <sub>IN</sub> ≤ 0.2 V, V <sub>IN</sub> ≥ V <sub>CC</sub> - 0.2 V				0.1 0.2	
ΔI <sub>CC</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 3.4 V§, f <sub>1</sub> = 0, Outputs open	0.5	2			mA
	V <sub>CC</sub> = 5.25 V, V <sub>IN</sub> = 3.4 V§, f <sub>1</sub> = 0, Outputs open				0.5 2	
I <sub>CCD</sub> ¶	V <sub>CC</sub> = 5.5 V, One input switching at 50% duty cycle, Outputs open, $\overline{OE}_A = \overline{OE}_B = \text{GND}$ , V <sub>IN</sub> ≤ 0.2 V or V <sub>IN</sub> ≥ V <sub>CC</sub> - 0.2 V	0.06	0.12			mA/ MHz
	V <sub>CC</sub> = 5.25 V, One input switching at 50% duty cycle, Outputs open, $\overline{OE}_A = \overline{OE}_B = \text{GND}$ , V <sub>IN</sub> ≤ 0.2 V or V <sub>IN</sub> ≥ V <sub>CC</sub> - 0.2 V				0.06 0.12	

† Typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

‡ Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

§ Per TTL-driven input (V<sub>IN</sub> = 3.4 V); all other inputs at V<sub>CC</sub> or GND

¶ This parameter is derived for use in total power-supply calculations.



**CY54FCT244T, CY74FCT244T**  
**8-BIT BUFFERS/LINE DRIVERS**  
**WITH 3-STATE OUTPUTS**

SCCS071 – OCTOBER 2001

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)**

PARAMETER	TEST CONDITIONS		CY54FCT244T		CY74FCT244T		UNIT	
			MIN	TYP†	MAX	MIN		TYP†
I <sub>C</sub> #	V <sub>CC</sub> = 5.5 V, Outputs open, OE <sub>A</sub> = OE <sub>B</sub> = GND	One bit switching at f <sub>1</sub> = 10 MHz at 50% duty cycle	V <sub>IN</sub> ≤ 0.2 V or V <sub>IN</sub> ≥ V <sub>CC</sub> - 0.2 V	0.7	1.4		mA	
			V <sub>IN</sub> = 3.4 V or GND	1	2.4			
		Eight bits switching at f <sub>1</sub> = 2.5 MHz at 50% duty cycle	V <sub>IN</sub> = 0.2 V or V <sub>IN</sub> ≥ V <sub>CC</sub> - 0.2 V	1.3	2.6			
			V <sub>IN</sub> = 3.4 V or GND	3.3	10.6			
	V <sub>CC</sub> = 5.25 V, Outputs open, OE <sub>A</sub> = OE <sub>B</sub> = GND	One bit switching at f <sub>1</sub> = 10 MHz at 50% duty cycle	V <sub>IN</sub> ≤ 0.2 V or V <sub>IN</sub> ≥ V <sub>CC</sub> - 0.2 V			0.7		1.4
			V <sub>IN</sub> = 3.4 V or GND			1		2.4
		Eight bits switching at f <sub>1</sub> = 2.5 MHz at 50% duty cycle	V <sub>IN</sub> = 0.2 V or V <sub>IN</sub> ≥ V <sub>CC</sub> - 0.2 V			1.3		2.6
			V <sub>IN</sub> = 3.4 V or GND			3.3		10.6
C <sub>i</sub>			5	10	5	10	pF	
C <sub>o</sub>			9	12	9	12	pF	

† Typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

# I<sub>C</sub> = I<sub>CC</sub> + ΔI<sub>CC</sub> × D<sub>H</sub> × N<sub>T</sub> + I<sub>CCD</sub> (f<sub>0</sub>/2 + f<sub>1</sub> × N<sub>1</sub>)

Where:

I<sub>C</sub> = Total supply current

I<sub>CC</sub> = Power-supply current with CMOS input levels

ΔI<sub>CC</sub> = Power-supply current for a TTL high input (V<sub>IN</sub> = 3.4 V)

D<sub>H</sub> = Duty cycle for TTL inputs high

N<sub>T</sub> = Number of TTL inputs at D<sub>H</sub>

I<sub>CCD</sub> = Dynamic current caused by an input transition pair (HLH or LHL)

f<sub>0</sub> = Clock frequency for registered devices, otherwise zero

f<sub>1</sub> = Input signal frequency

N<sub>1</sub> = Number of inputs changing at f<sub>1</sub>

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I<sub>CC</sub> formula.



**CY54FCT244T, CY74FCT244T**  
**8-BIT BUFFERS/LINE DRIVERS**  
**WITH 3-STATE OUTPUTS**

SCCS071 – OCTOBER 2001

**switching characteristics over operating free-air temperature range (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CY54FCT244T		CY54FCT244AT		CY54FCT244CT		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	D	O	1.5	7	1.5	5.1	1.5	4.6	ns
t <sub>PHL</sub>			1.5	7	1.5	5.1	1.5	4.6	
t <sub>PZH</sub>	$\overline{OE}$	O	1.5	8.5	1.5	6.5	1.5	6.5	ns
t <sub>PZL</sub>			1.5	8.5	1.5	6.5	1.5	6.5	
t <sub>PHZ</sub>	$\overline{OE}$	O	1.5	7.5	1.5	5.9	1.5	5.7	ns
t <sub>PLZ</sub>			1.5	7.5	1.5	5.9	1.5	5.7	

**switching characteristics over operating free-air temperature range (see Figure 1)**

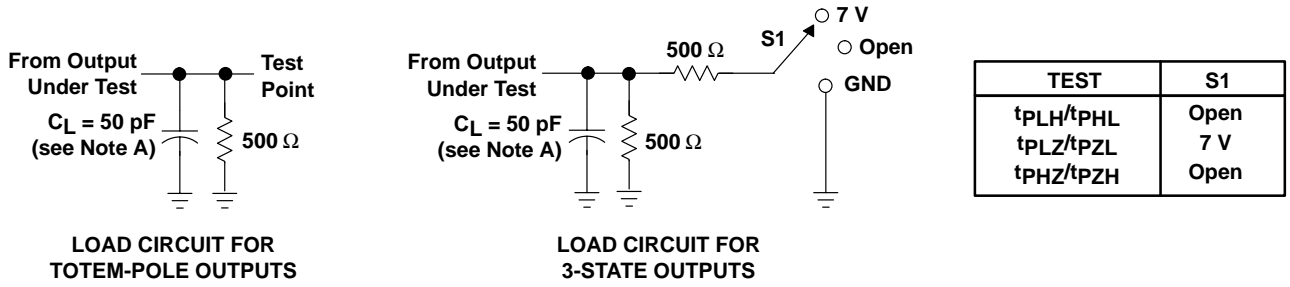
PARAMETER	FROM (INPUT)	TO (OUTPUT)	CY74FCT244T		CY74FCT244AT		CY74FCT244CT		CY74FCT244DT		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	D	O	1.5	6.5	1.5	4.6	1.5	4.1	1.5	3.6	ns
t <sub>PHL</sub>			1.5	6.5	1.5	4.6	1.5	4.1	1.5	3.6	
t <sub>PZH</sub>	$\overline{OE}$	O	1.5	8	1.5	6.2	1.5	5.8	1.5	4.8	ns
t <sub>PZL</sub>			1.5	8	1.5	6.2	1.5	5.8	1.5	4.8	
t <sub>PHZ</sub>	$\overline{OE}$	O	1.5	7	1.5	5.6	1.5	5.2	1.5	4	ns
t <sub>PLZ</sub>			1.5	7	1.5	5.6	1.5	5.2	1.5	4	



**CY54FCT244T, CY74FCT244T**  
**8-BIT BUFFERS/LINE DRIVERS**  
**WITH 3-STATE OUTPUTS**

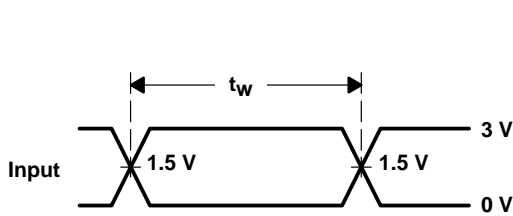
SCCS071 – OCTOBER 2001

**PARAMETER MEASUREMENT INFORMATION**

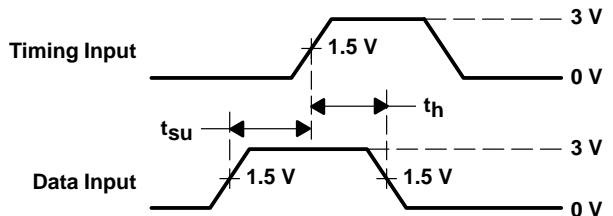


**LOAD CIRCUIT FOR TOTEM-POLE OUTPUTS**

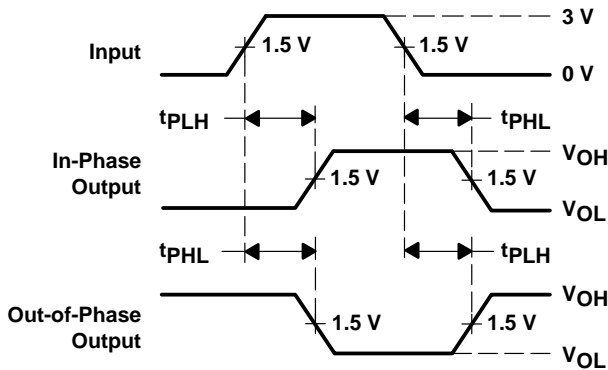
**LOAD CIRCUIT FOR 3-STATE OUTPUTS**



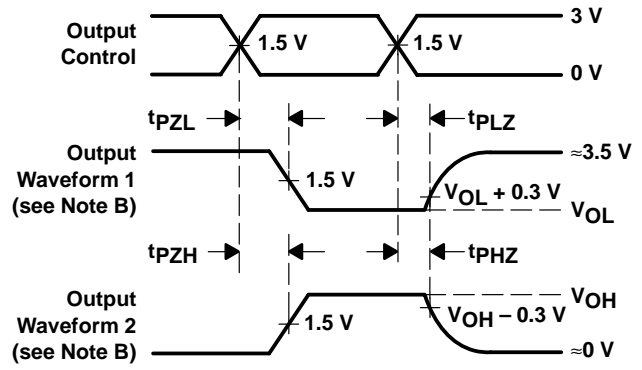
**VOLTAGE WAVEFORMS PULSE DURATION**



**VOLTAGE WAVEFORMS SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS**



**VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING**

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. The outputs are measured one at a time with one input transition per measurement.

**Figure 1. Load Circuit and Voltage Waveforms**



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9220301M2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9220301M2A CY54FCT 244TLMB	<a href="#">Samples</a>
5962-9220301MRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9220301MR A CY54FCT244TDMB	<a href="#">Samples</a>
5962-9220301MSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9220301MS A CY54FCT244TW	<a href="#">Samples</a>
5962-9220302M2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9220302M2A CY54FCT 244ATLMB	<a href="#">Samples</a>
5962-9220302MRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9220302MR A CY54FCT244ATDM B	<a href="#">Samples</a>
5962-9220302MSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9220302MS A CY54FCT244ATW	<a href="#">Samples</a>
5962-9220303M2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9220303M2A	<a href="#">Samples</a>
5962-9220303MRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9220303MR A CY54FCT244CTDM B	<a href="#">Samples</a>
CY54FCT244ATDMB	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9220302MR A CY54FCT244ATDM B	<a href="#">Samples</a>
CY54FCT244ATLMB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9220302M2A CY54FCT 244ATLMB	<a href="#">Samples</a>
CY54FCT244ATW	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9220302MS A	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
										CY54FCT244ATW	
CY54FCT244CTDMB	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9220303MR A CY54FCT244CTDM B	<a href="#">Samples</a>
CY54FCT244TDMB	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9220301MR A CY54FCT244TDMB	<a href="#">Samples</a>
CY54FCT244TLMB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9220301M2A CY54FCT 244TLMB	<a href="#">Samples</a>
CY54FCT244TW	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9220301MS A CY54FCT244TW	<a href="#">Samples</a>
CY74FCT244ATPC	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	CY74FCT244ATPC	<a href="#">Samples</a>
CY74FCT244ATPCE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	CY74FCT244ATPC	<a href="#">Samples</a>
CY74FCT244ATQCT	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT244A	<a href="#">Samples</a>
CY74FCT244ATQCTE4	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT244A	<a href="#">Samples</a>
CY74FCT244ATQCTG4	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT244A	<a href="#">Samples</a>
CY74FCT244ATSOC	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244A	<a href="#">Samples</a>
CY74FCT244ATSOCG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244A	<a href="#">Samples</a>
CY74FCT244ATSOCT	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244A	<a href="#">Samples</a>
CY74FCT244ATSOCTE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244A	<a href="#">Samples</a>
CY74FCT244CTQCT	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT244C	<a href="#">Samples</a>
CY74FCT244CTSOC	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244C	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CY74FCT244CTSOCT	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	-40 to 85		
CY74FCT244CTSOCTG4	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	-40 to 85		
CY74FCT244DTSOC	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244D	Samples
CY74FCT244DTSOCT	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244D	Samples
CY74FCT244DTSOCTE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244D	Samples
CY74FCT244TQCT	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT244	Samples
CY74FCT244TSOC	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244	Samples
CY74FCT244TSOCG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244	Samples
CY74FCT244TSOCT	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT244ATQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT244ATSOCT	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
CY74FCT244CTQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT244DTSOCT	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
CY74FCT244TQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT244TSOCT	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT244ATQCT	SSOP	DBQ	20	2500	367.0	367.0	38.0
CY74FCT244ATSOCT	SOIC	DW	20	2000	367.0	367.0	45.0
CY74FCT244CTQCT	SSOP	DBQ	20	2500	367.0	367.0	38.0
CY74FCT244DTSOCT	SOIC	DW	20	2000	367.0	367.0	45.0
CY74FCT244TQCT	SSOP	DBQ	20	2500	367.0	367.0	38.0
CY74FCT244TSOCT	SOIC	DW	20	2000	367.0	367.0	45.0

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

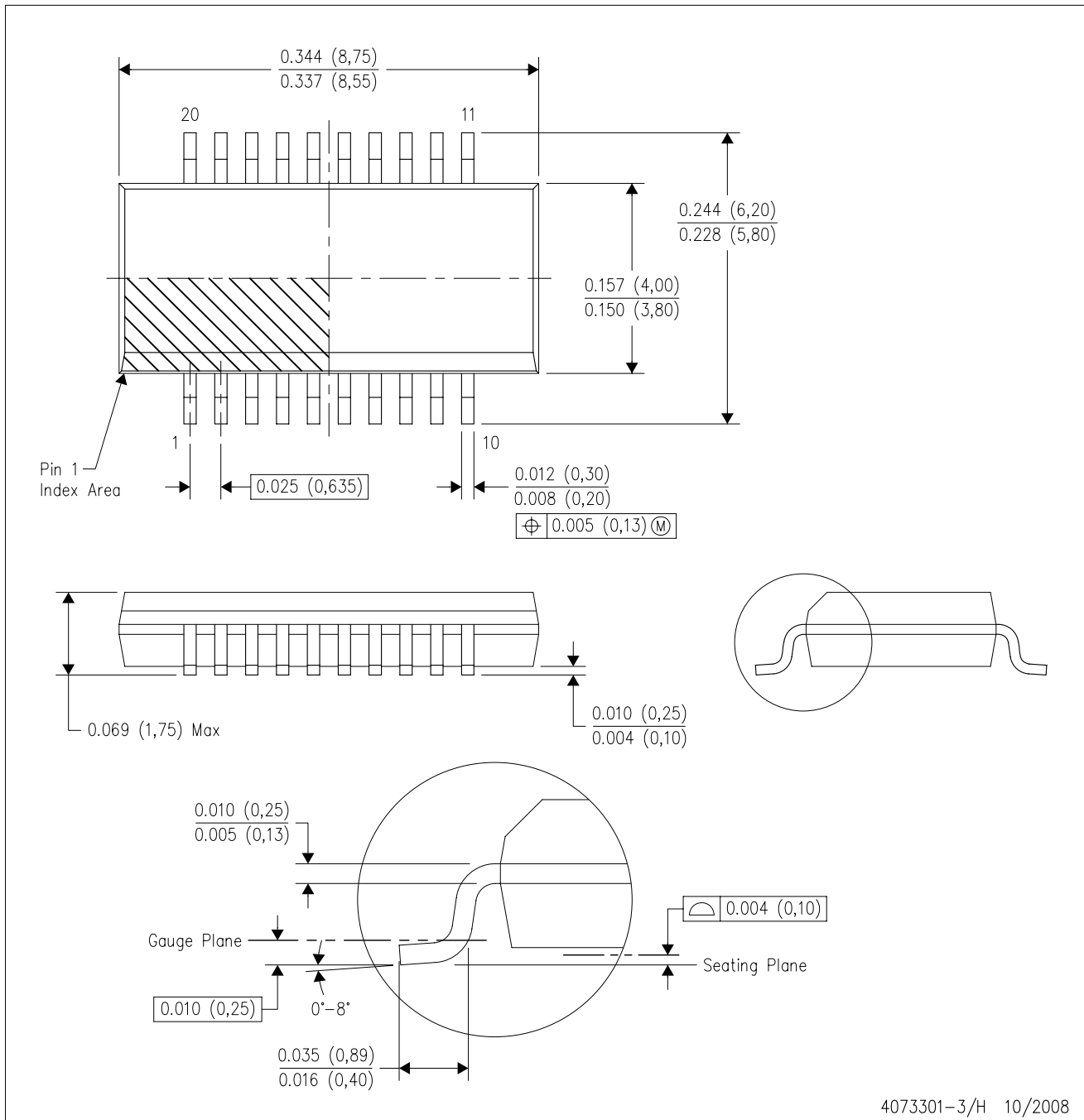


4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

DBQ (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE

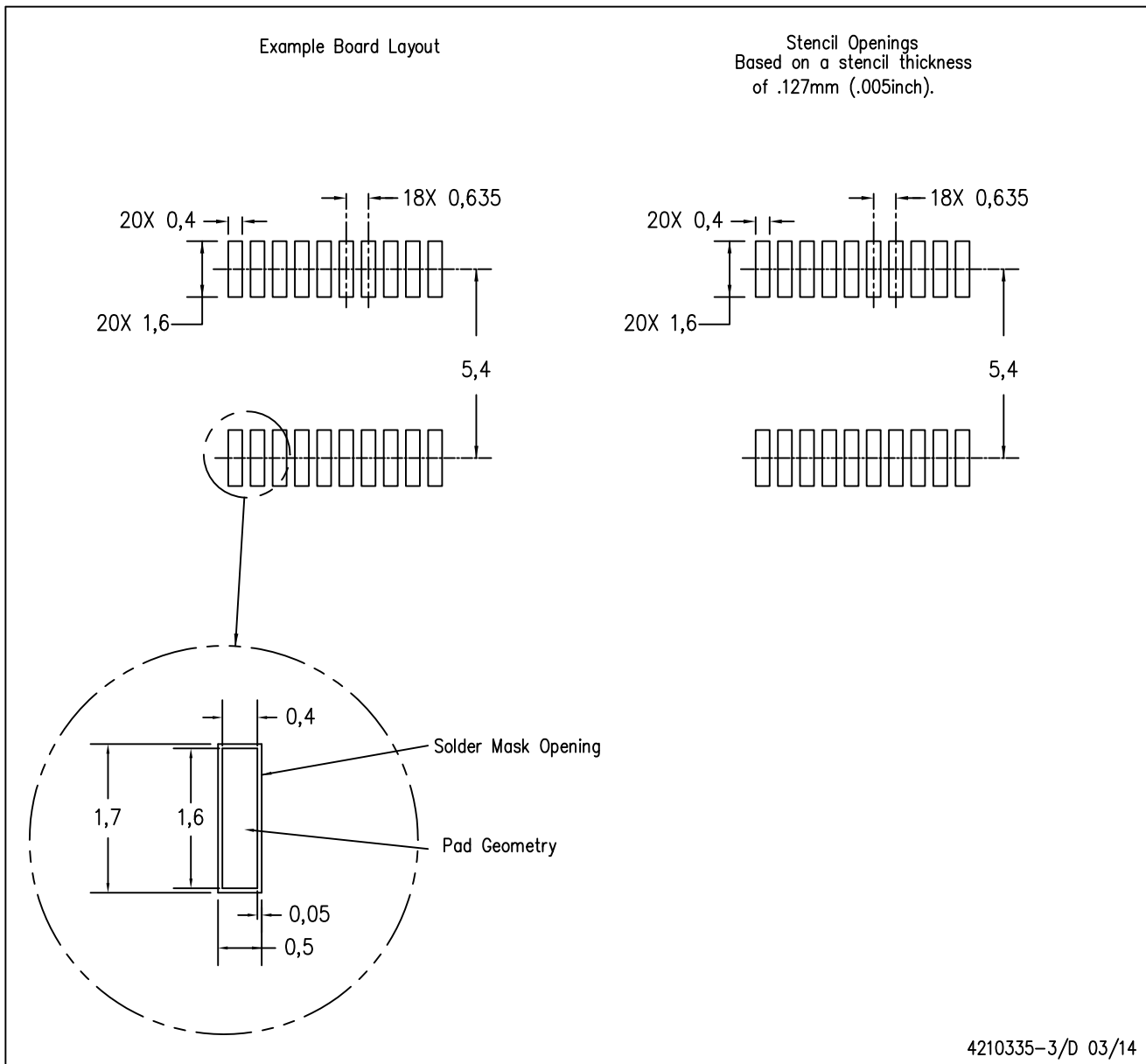


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
  - D. Falls within JEDEC MO-137 variation AD.



DBQ (R-PDSO-G20)

PLASTIC SMALL OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

# DW0020A



# PACKAGE OUTLINE

## SOIC - 2.65 mm max height

SOIC



4220724/A 05/2016

### NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

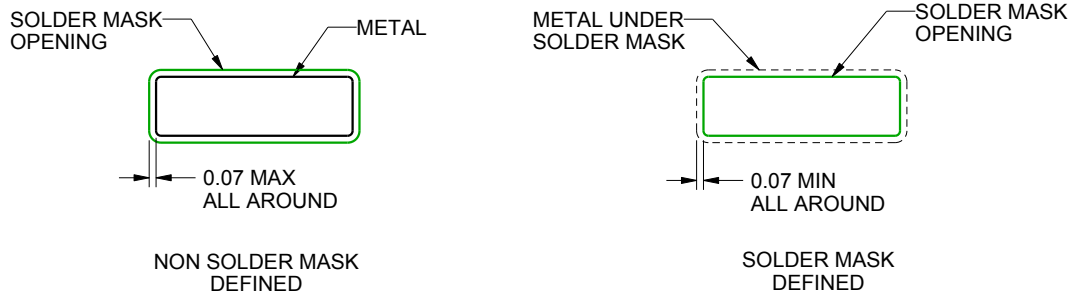
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

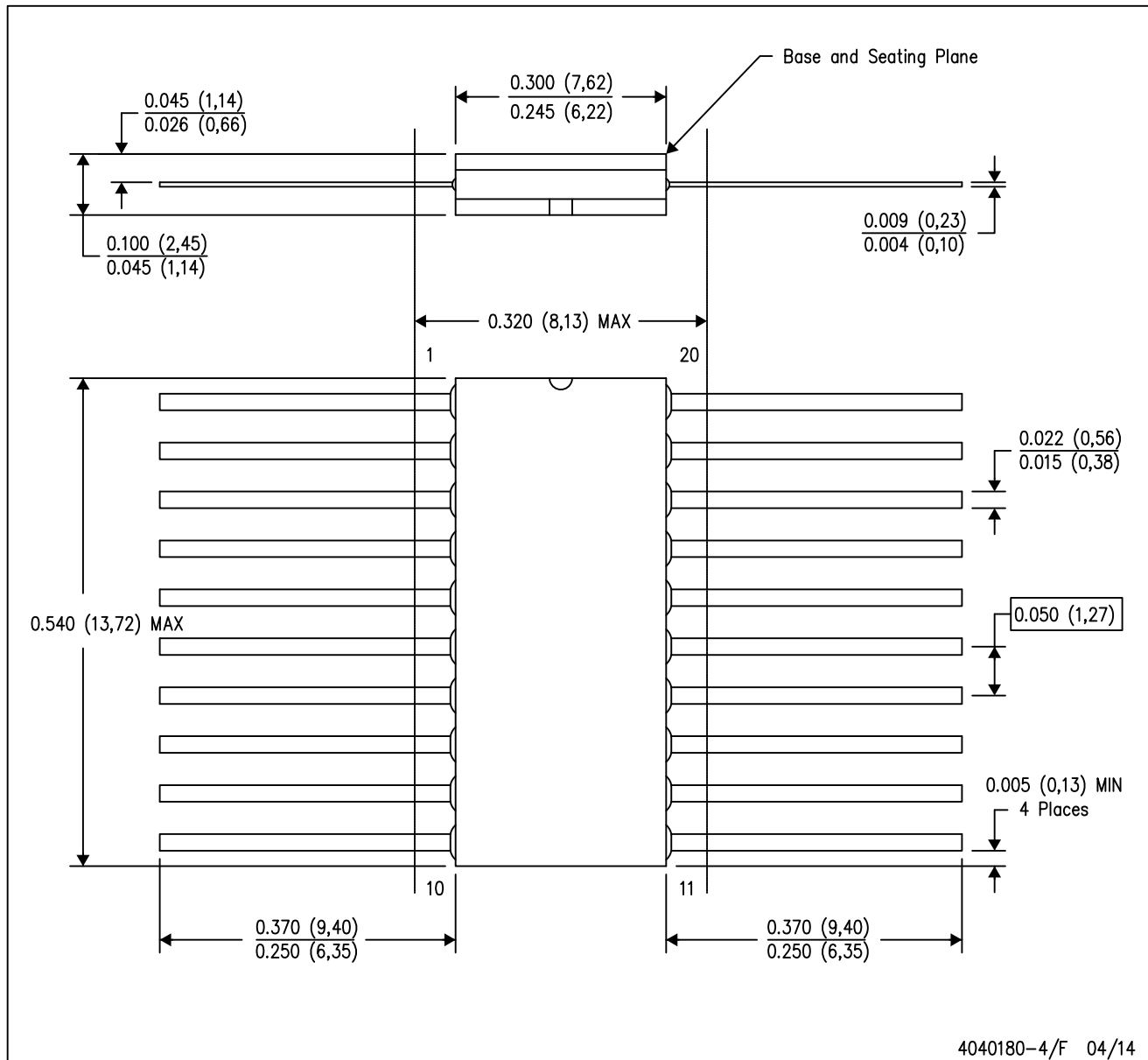
4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within Mil-Std 1835 GDFP2-F20

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